

# TPC electronics update

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- We should follow the STAR iTPC electronics development
  - Materials are being collected.
- The iTPC group decided designing electronics with SAMPA chips
  - The first non-packaged SAMPA chip should come out early June
  - A prototype testing board for the non-packaged chips is designed and will be manufactured by ALICE-affiliated French group by July.
  - Tonko will get one board for local STAR preliminary tests.
  - The packaged chip is expected in mid/late July at which point STAR will have their own board for further testing and other integration
- No formal design of the electronics exists

# Readout scheme

